SECTRON ELECTRONICS CO., LTD.

APPROVAL SHEET



(GLASS Type)

CUST	OMER:					
DESC	RIPTION:	SMD50)32-Glass 25.0	00N	/IHz Quartz Crystal Resonato	or
	UFACTURER PART NO.: OMER PART NO:	FTX2	5.000M18SI	M50	G-2P	
	IN MODEL:					
REVISION		A1				
		承	认	Δ	APPROVAL	
	工程部 TECHNOLOGY DEPT.		品质部 LITY DEPT.		采购部 PURCHASING DEPT.	

Date: <u>March 23, 2022</u>

SECTRON ELECTRONICS CO., LTD

Rev	Revise page	Revise contents	<u>Date</u>	Ref.No.	<u>Reviser</u>
A1	ALL	Initial released		N/A	DavidJiang

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1. QUARTZ CRYSTAL UNIT SPECIFICATION

1.1 Nominal Frequency: 25.000MHz

1.2 Holder type: FTX531GA (SMD5032 Glass 2PAD)

1.3 Mode of oscillation: Fundamental

1.4 Frequency tolerance: ±20ppm at 25℃±3℃

1.5 Equivalent resistance: 40ohms max

1.6 Operating temperature range: -20° C To $+70^{\circ}$ C

1.7 Storage temperature range: -40° C To +85°C

1.8 Frequency Stability: ±30ppm at -20°C To +70°C

1.9 Loading capacitance (CL): 18.0pF

1.10 Drive level: 100 uW Typical (300 uW max)

1.11 Shunt Capacitance: 5.0pF max

1.12 Insulation resistance : More than $500M\Omega$ at DC 100V

1.13 Circuit: Measured in HP/E5100A,S&A 250B

1.14 Aging: ± 3 ppm Max ($\pm 25^{\circ}$ C 1st Year)

1.15 Dimensions and marking Refer to page.3

1.16 Emboss carrier tape & reel Refer to page.5 and page.6

1.17 Note:

Standard atmospheric conditions

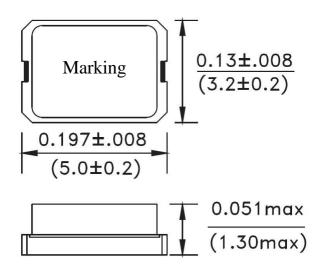
Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

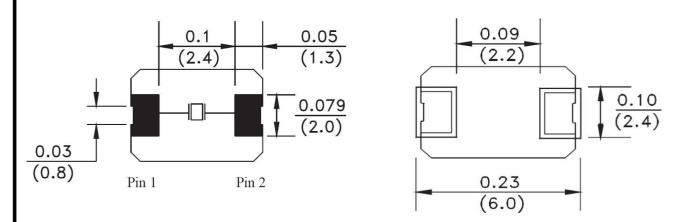
Ambient temperature : 25±3℃

Relative humidity: 40%~70%

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2. FTX531GA MARKING & DIMENSIONS





Recommended Solder Pad Layout:

*Marking should be printed as following:

Logo, Nominal Frequency

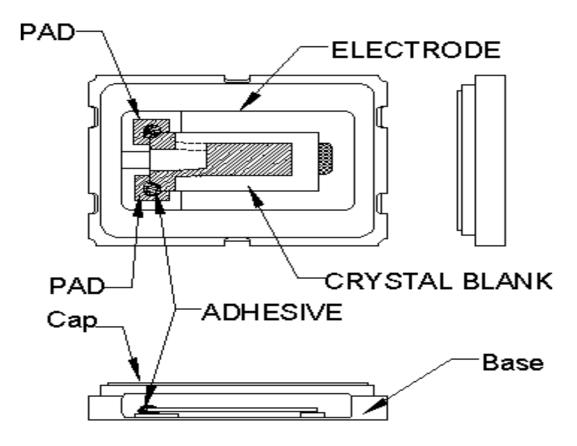
*Nominal frequency = 3 number after decimal point MAX.

(ex. $12.000 \text{ MHz} \rightarrow 12.000$)

Marking: Laser marking or Ink marking.

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3. INSIDE STRUCTURE



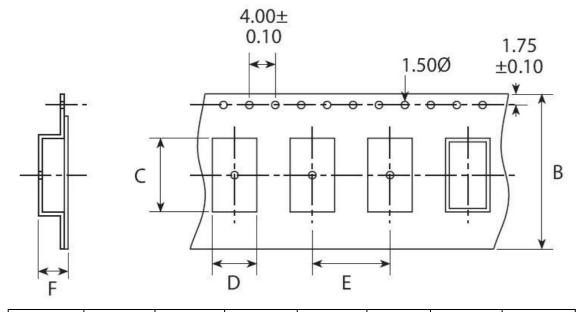
Reference drawing

reference araning
Base:
Alumina Ceramic (Al ₂ O ₃)
Metallized Pad: W
Ni Plating
Au Plating
Cap:
Alumina Ceramic (Al ₂ O ₃)
(3) Crystal Enclosure Seal:
Seal Glass
(4) Crystal Blank
Rectangular At-Cut Quartz Crystal Blank
(5) Adhesive
Silver Conductive Polyimide Resin
(6) Electrode
Ag
(7)PAD
Alumina Ceramic (W. Ni. Au)

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4. FTX531G EMBOSS CARRIER TAPE & REEL

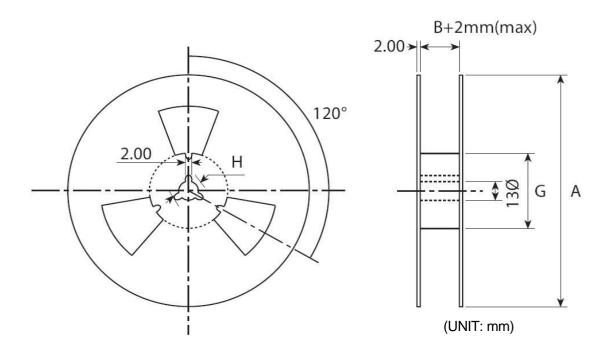
a.) Dimensions of Carrier Tape



	A	В	С	D	Е	F	G
SMD5032	178±2.0	12.0±0.3	5.40±0.10	3.60 ± 0.10	8.0±0.1	1.1 ± 0.1	60.5 ± 1.0

b.) Dimensions of Reel

(UNIT: mm)



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c.) Storage condition

Temperature: +40deg.C Max. Relative Humidity: 80% Max.

d.) Standard packing quantity

1,000PCS / REEL

e.) Material of the tape

Tape	Material
Carrier tape	A – PET
Top tape	Polyester

- f.) Label contents
 - .The type of product
 - .Our specification No.
 - .Your Part No.
 - .Lot No.
 - .Nominal Frequency
 - .Quantity
 - .Our Company Name

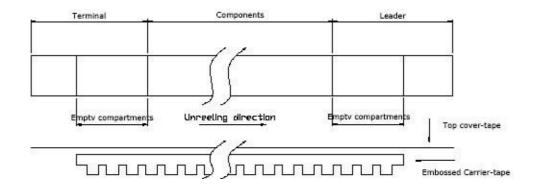
Sticks label for every reel.

REMAKS	
FREQUENCY	
HOLDER TYPE	
PR. NO:	
PO NO	
PART NUMBER	

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g.) Taping dimension

Leader	Cover-tape	The length of cover-tape in the leader is more than 400 mm including empty embossed area.	
Leauei	Carrier-tape	After all products were packaged, must remain more than twenty pieces or 400 mm empty area, which should be sealed by cover-tape.	
.	Cover-tape The tip of cover-tape shall be fixed temporary by paper tape and roll are the core of reel one round.		
Terminal	Carrier-tape	The empty embossed area which are sealed by top cover-tape must remain more the 40 mm.	



h.) Joint of tape

The carrier-tape and top cover-tape should not be jointed.

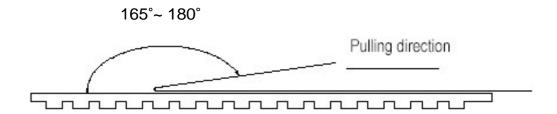
i.) Release strength of cover tape

It has to between 0.1N to 0.7N under following condition.

Pulling direction 165° to 180°

Speed 300mm/min.

Otherwise unless specified.

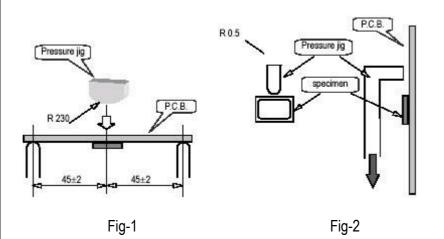


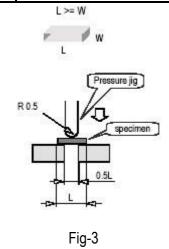
Other standards shall be based on JIS C 0806-1990.

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5. Mechanical Endurance: Provided that measurement shall be carried out afterletting it alone in the room temperature for 1 hour.

	Item	Conditions	Specifications
5.1	Drop	Method: fallen on the concrete (thickness is 3cm or more) Height: 75 cm Direction: each direction of 3 mutually perpendicular (x, y, z) axis. Number of shocks: 2 shocks in each direction	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
5.2	Vibration	Should be satisfied after supplying following vibration. (1)Vibration Frequency: 10~55Hz (2)Cycle: 1 to 2 Min. (3)Full Cycle: 1.5mm P-P. (4)Direction: X.Y.Z (5)Time: 2 Hours / Each Direction	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
5.3	Substrate Bending	Mount the specimen on substrate. Apply the following pressure Direction: see Fig -1 Speed: 0.5 mm/sec Hours: 5 ± 1 sec Amount of substrate: 3 mm Max.	Without mechanical
5.4	Adhesion	Mount the specimen on substrate. Apply the following pressure Direction: see Fig -2 Weight: 10N Hours: 10 \pm 1 sec	damage such as breaks. Without electrode peeling. Electrical characteristics shall be satisfied.
5.5	Body strength	Mount the specimen on substrate. Apply the following pressure Direction: see Fig -3 Weight: 10N Hours: 10 ± 1 sec	





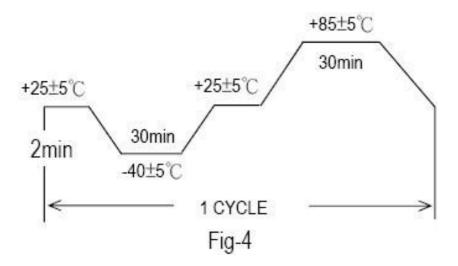
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5.6	Seal	Less than 5.0 x 10 ⁻⁸ atm.cc/sec by Helium leak detector. Also, no serial bubble is observed by Fluorinate tests.	
5.7	Solder ability	3 sec Dip in 235°C±5°C solder. (Use ROSIN type flux for solder.)	More than 90% of lead shall be covered by new solder.
5.8	Resistance to Soldering Heat	Run in Reflow Reflow soldering shall be allowed Only two(2) time. Available for Lead Free Soldering 260 deg.C 160~180de (1) Preheat 160~180 deg.C 120sec. (2) Primary heat 220 deg.C 60sec. (3) Peak 260 deg.C 10sec. Max.	Freq. Drift ±10ppm Max. Resistance Drift ±20% Max.

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6. Environmental Endurance: Provided that measurement shall be carried out afterletting it alone in the room temperature for 1 hour.

	Item	Conditions	Specifications
6.1	Humidity	Should be satisfied after letting it alone at +60°C±2°C in humidity of 90%∼95% for 250 hours.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
6.2	Storage in Low Temperature	Should be satisfied after letting it alone at -40 $^{\circ}\text{C}\pm\!3^{\circ}\text{C}$ for 250 hours.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
6.3	Storage in High Temperature	Should be satisfied after letting it alone at +85℃±3℃ for 250 hours.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max
6.4	Temperature Cycle	Should be satisfied after supplying the following temperature cycle (100 cycles). (Refer to Fig-4). Temperature shift from low to high, high to low shall be done in 1°C/min.	Freq. Drift ± 5ppm Max Resistance Drift ± 15% Max



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